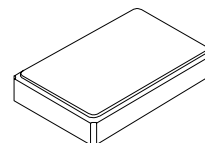


**XTL1060**

**26.00000 MHz  
Crystal Unit**



**SM2520-4 Case**

## Features:

- Surface Mount Hermetic Package
- Excellent Reliability Performance
- Good Frequency Perturbation and Stability over temperature
- Ultra Miniature Package
- Moisture Sensitivity Level (MSL) : Level-1

<b>XTL1060</b>	<b>Specification</b>
Nominal Frequency	26.000000 MHz
Mode of Oscillation	Fundamental
Storage Temperature Range	-40°C to +85°C
Operating Temperature Range	-20°C to +85°C
Frequency Stability over Operating Temperature Range	+/-10 ppm (referred to the value at 25°C)
Frequency Make Tolerance (FL)	+/-10 ppm @ 25°C +/- 3°C
Equivalent Series Resistance (ESR)	60 $\Omega$ max
Nominal Drive Level	10uW typical and 100uW max
Shunt Capacitance (Co)	3.0 pF max
Load Capacitance (CL)	10 pF
Aging	+/-1ppm/year
Insulation Resistance	500 M $\Omega$ min./DC 100V
Marking	Laser Marking
Unit Weight	9.5 +/-0.5mg



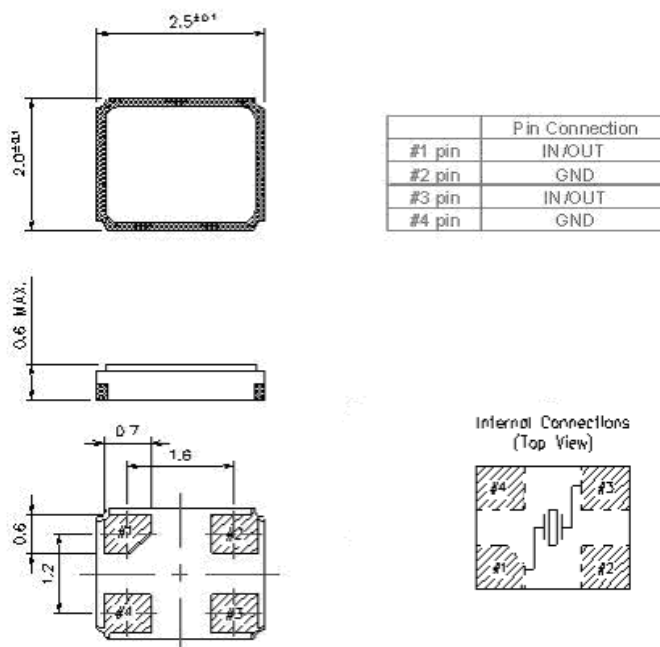
**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

### NOTES:

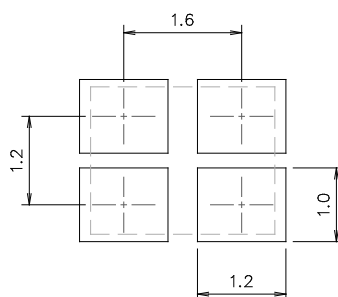
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. This component was always RoHS compliant from the first date of manufacture.

## Mechanical Dimensions (mm):

Base



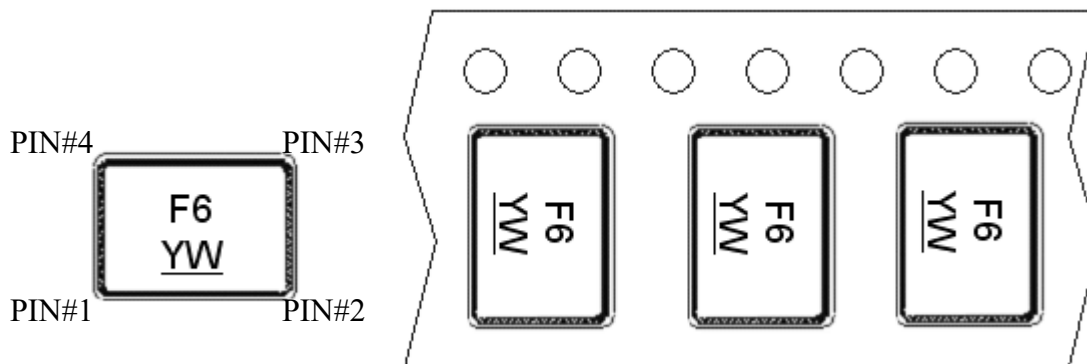
## Recommended Land Pattern: (unit: mm)



## Marking:

Line 1: Letter ( F6 )

Line 2: Year Code ( Y ) + Week Code ( W )



The inner vision of PIN#1,PIN#4 side is XTAL blank mounting pad.

Year Code ( Y )

Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	0	1	2	3	4	5	6	7	8	9

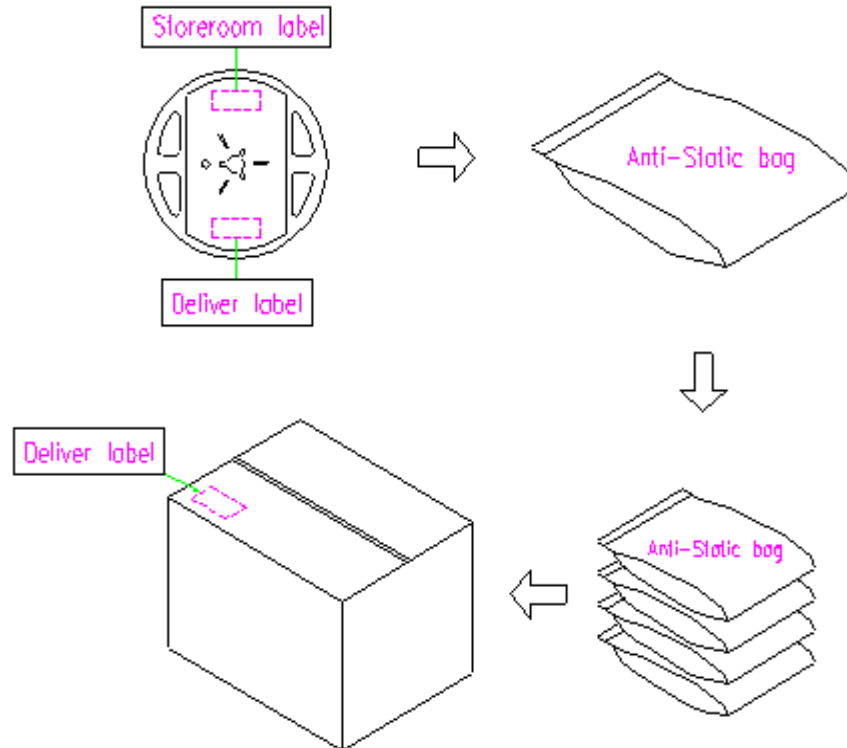
Week Code ( W )

Date Code Table												
WK01	WK02	WK03	WK04	WK05	WK06	WK07	WK08	WK09	WK10	WK11	WK12	WK13
A	B	C	D	E	F	G	H	I	J	K	L	M
WK14	WK15	WK16	WK17	WK18	WK19	WK20	WK21	WK22	WK23	WK24	WK25	WK26
N	O	P	Q	R	S	T	U	V	W	X	Y	Z
WK27	WK28	WK29	WK30	WK31	WK32	WK33	WK34	WK35	WK36	WK37	WK38	WK39
a	b	c	d	e	f	g	h	i	j	k	l	m
WK40	WK41	WK42	WK43	WK44	WK45	WK46	WK47	WK48	WK49	WK50	WK51	WK52
n	o	p	q	r	s	t	u	v	w	x	y	z

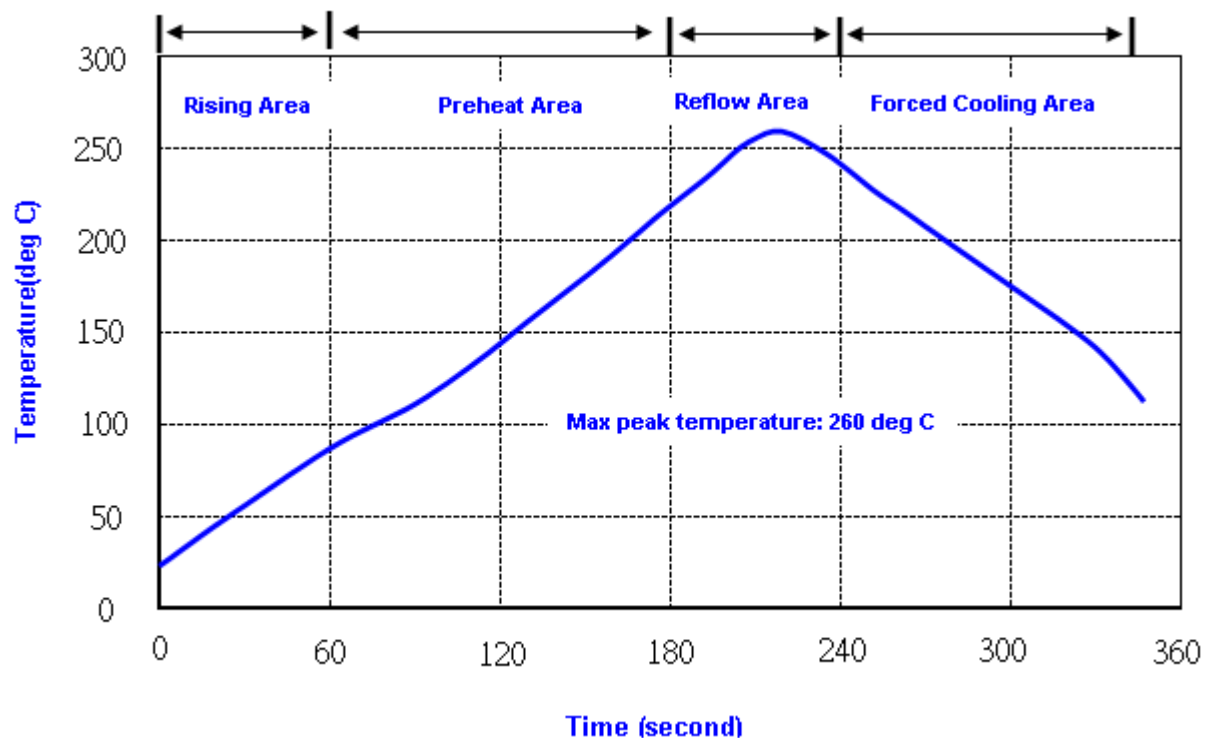


## Packing Quantity/Packing:

3K pcs maximum per reel



## Reflow Profile:



**Note:** 1. Max peak temperature: 260 $\pm$ 5 deg C; Time: 10 $\pm$ 2 sec  
2. Temperature: 217 $\pm$ 5 deg C; Time: 90~100 sec

## Reliability Specifications

Test name	Test process / method	Reference standard
<b>Mechanical characteristics</b>		
resistance to Soldering heat (IR reflow)	Temp./ Duration : 265°C /10sec ×2 times Total time : 4min.(IR-reflow)	EIAJED-4701  -300(301)M(II)
Vibration	Total peak amplitude : 1.5mm Vibration frequency : 10 to 2000 Hz Sweep period : 20 minute Vibration directions : 3 mutually perpendicular Duration : 2 hr / direc.	MIL-STD 202G method 204
Mechanical Shock	directions : 3 impacts per axis Acceleration : 3000g's, +20/-0 % Duration : 0.3 ms (total 18 shocks) Waveform : Half-sine	MIL-STD 202G method 213
Solderability	Solder Temperature:265±5°C Duration time: 5±0.5 seconds.	J-STD-002
<b>Environmental characteristics</b>		
Thermal Shock	Heat cycle conditions -40 °C (30min) ↔ 85 °C (30min) * cycle time : 10 times	MIL-STD 883G method 1010.8
Humidity test	Temperature : 85 ± 2 °C Relative humidity : 85% Duration : 96 hours	MIL-STD 202G method 103
Dry heat ( Aging test )	Temperature : 125 ± 2 °C Duration : 168 hours	MIL-STD 202G method 108A
Cold resistance (Low Temp Storage)	Temperature : -40 ± 2 °C Duration : 96 hours	IEC 60068-2-1